IXYS

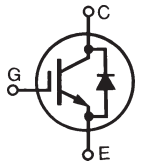
Advance Technical Information

BiMOSFET™ Monolithic Bipolar MOS Transistor High Voltage, High Frequency

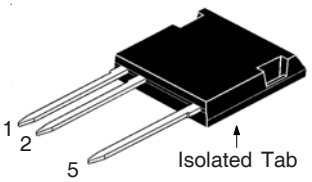
IXBF50N360

(Electrically Isolated Tab)

V_{CES} = 3600V
I_{C110} = 28A
$V_{CE(sat)} \leq$ 2.9V



ISOPLUS i4-Pak™



1 = Gate 5 = Collector
2 = Emitter

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 150°C	3600	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	3600	V
V_{GES}	Continuous	± 20	V
V_{GEM}	Transient	± 30	V
I_{C25}	T_C = 25°C	70	A
I_{C110}	T_C = 110°C	28	A
I_{CM}	T_C = 25°C, 1ms	420	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 125°C, R_G = 5Ω Clamped Inductive Load	I_{CM} = 200 0.8 • V_{CES}	A V
t_{SC} (SCSOA)	V_{GE} = 15V, T_J = 125°C, R_G = 10Ω, V_{CE} = 1500V, Non-Repetitive	10	μs
P_C	T_C = 25°C	290	W
T_J		- 55 ... +150	°C
T_{JM}		150	°C
T_{stg}		- 55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	Plastic Body for 10s	260	°C
F_C	Mounting Force with Clip	30..170 / 7..36	N/lb
V_{ISOL}	50/60Hz, 5 Seconds	4000	V~
Weight		8	g

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{CES}	I_C = 250μA, V_{GE} = 0V	3600			V
$V_{GE(th)}$	I_C = 250μA, V_{CE} = V_{GE}	3.0		5.0	V
I_{CES}	V_{CE} = 0.8 • V_{CES}, V_{GE} = 0V			25	μA
	Note 2, T_J = 100°C		50		μA
I_{GES}	V_{CE} = 0V, V_{GE} = ± 20V			±200	nA
$V_{CE(SAT)}$	I_C = 50A, V_{GE} = 15V, Note 1		2.4	2.9	V
	T_J = 125°C		3.0		V

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 4000V~ Electrical Isolation
- High Blocking Voltage
- High Frequency Operation

Advantages

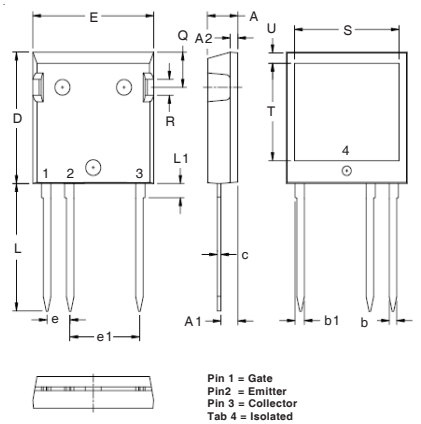
- Low Gate Drive Requirement
- High Power Density

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- Uninterruptible Power Supplies (UPS)
- Laser Generators
- Capacitor Discharge Circuits
- AC Switches

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.
g_{fs}	I_C = 50A, V_{CE} = 10V, Note 1	24	40	S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		3990	pF
C_{oes}			195	pF
C_{res}			100	pF
$Q_{g(on)}$	I_C = 50A, V_{GE} = 15V, V_{CE} = 1000V		210	nC
Q_{ge}			27	nC
Q_{gc}			77	nC
$t_{d(on)}$	**Resistive load, T_J = 25°C**		46	ns
t_r	I_C = 50A, V_{GE} = 15V		420	ns
$t_{d(off)}$	V_{CE} = 960V, R_G = 5Ω		205	ns
t_f			1750	ns
$t_{d(on)}$	**Resistive load, T_J = 125°C**		44	ns
t_r	I_C = 50A, V_{GE} = 15V		845	ns
$t_{d(off)}$	V_{CE} = 960V, R_G = 5Ω		210	ns
t_f			1670	ns
R_{thJC}				0.43 °C/W
R_{thCS}			0.15	°C/W

ISOPLUS i4-Pak™ (HV) Outline



Pin 1 = Gate
Pin2 = Emitter
Pin 3 = Collector
Tab 4 = Isolated

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.190	.205	4.83	5.21
A1	.102	.118	2.59	3.00
A2	.046	.085	1.17	2.16
b	.045	.055	1.14	1.40
b1	.058	.068	1.47	1.73
C	.020	.029	0.51	0.74
D	.819	.840	20.80	21.34
E	.770	.799	19.56	20.29
e	.150 BSC		3.81 BSC	
e1	.450 BSC		11.43 BSC	
L	.780	.840	19.81	21.34
L1	.083	.102	2.11	2.59
Q	.210	.244	5.33	6.20
R	.100	.180	2.54	4.57
S	.660	.690	16.76	17.53
T	.590	.620	14.99	15.75
U	.065	.080	1.65	2.03

Reverse Diode

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max
V_F	I_F = 50A, V_{GE} = 0V, Note 1			3.0 V
t_{rr}	I_F = 25A, V_{GE} = 0V, $-di_F/dt$ = 100A/μs		1.7	μs
I_{RM}	V_R = 100V, V_{GE} = 0V		48	A
Q_{RM}			40	μC

Notes:

1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.
2. Device must be heatsunk for high-temperature leakage current measurements to avoid thermal runaway.

ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

Fig. 1. Output Characteristics @ T_J = 25ºC

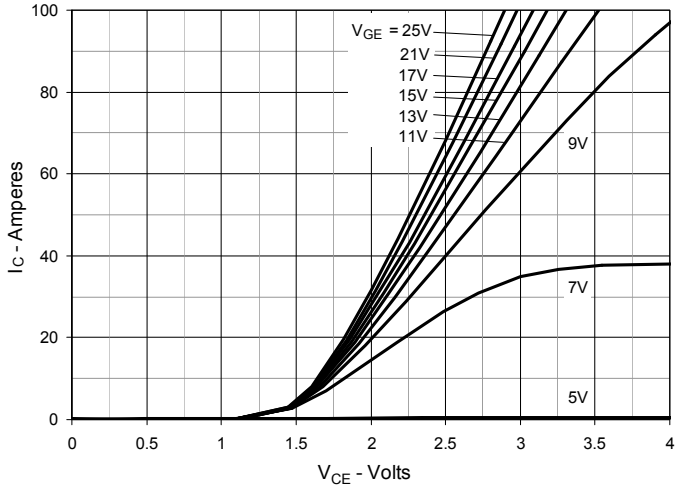


Fig. 2. Extended Output Characteristics @ T_J = 25ºC

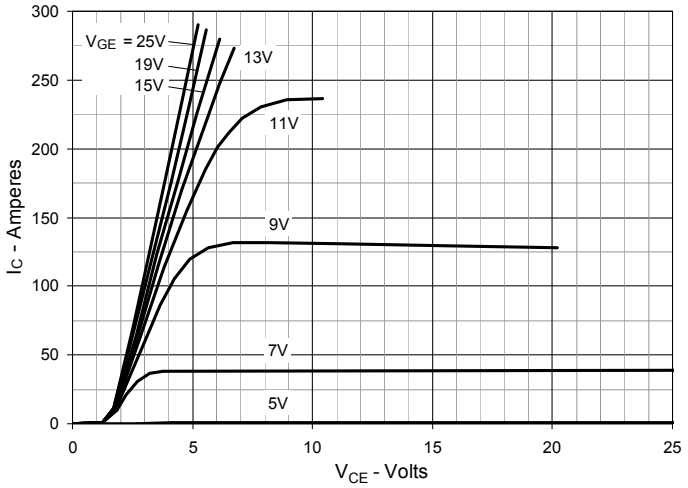


Fig. 3. Output Characteristics @ T_J = 125ºC

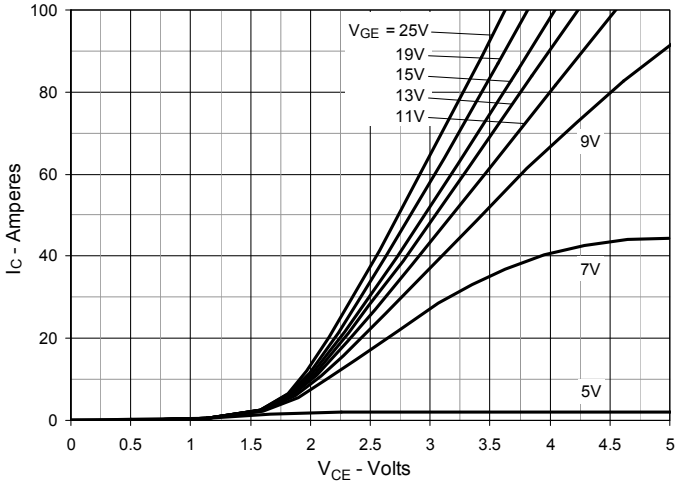


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

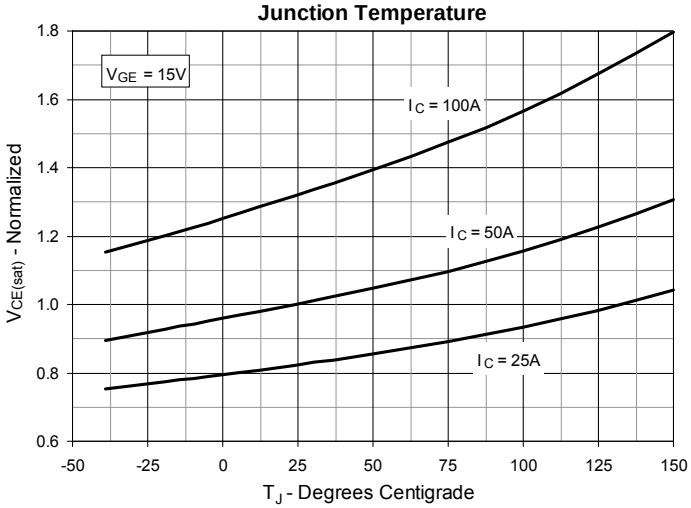


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

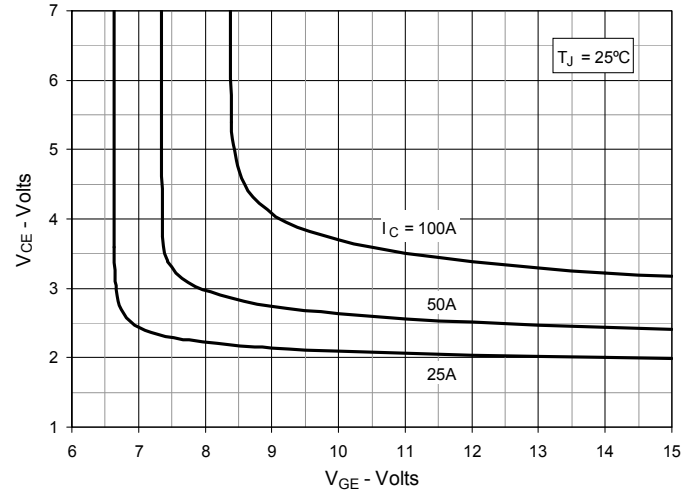


Fig. 6. Input Admittance

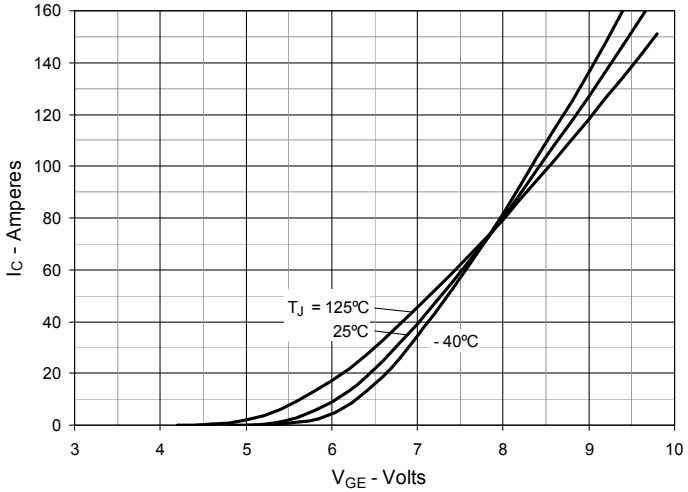


Fig. 7. Transconductance

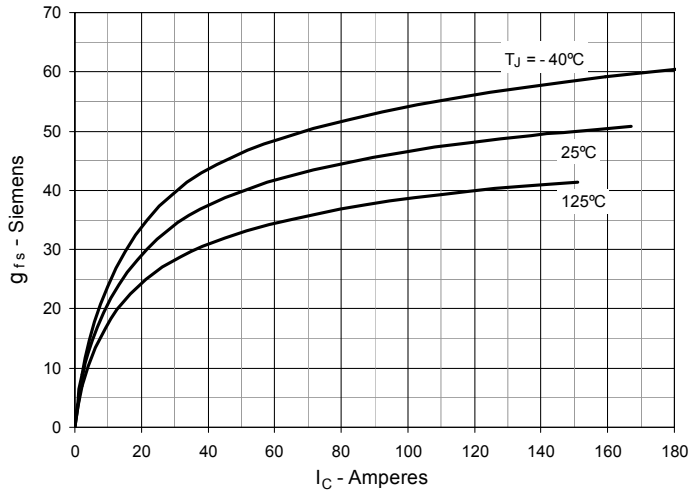


Fig. 8. Gate Charge

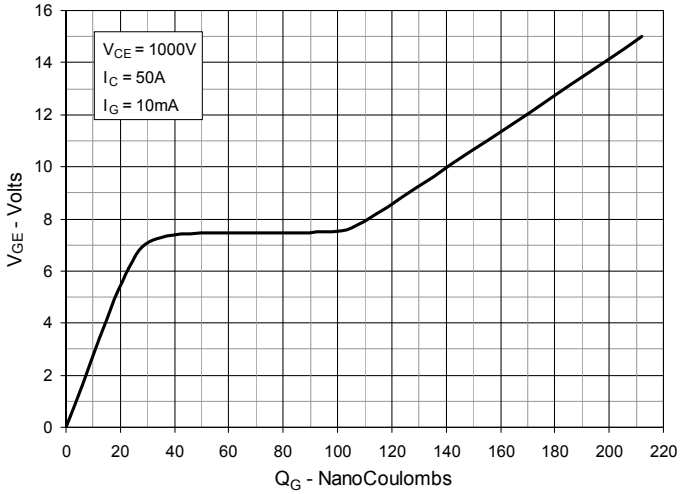


Fig. 9. Forward Voltage Drop of Intrinsic Diode

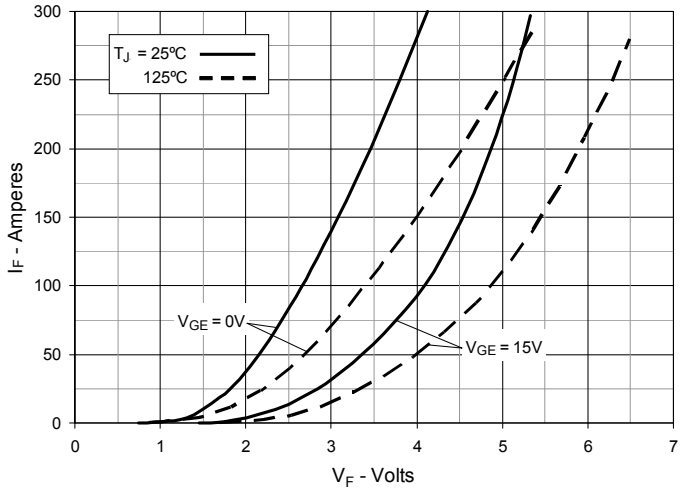


Fig. 10. Capacitance

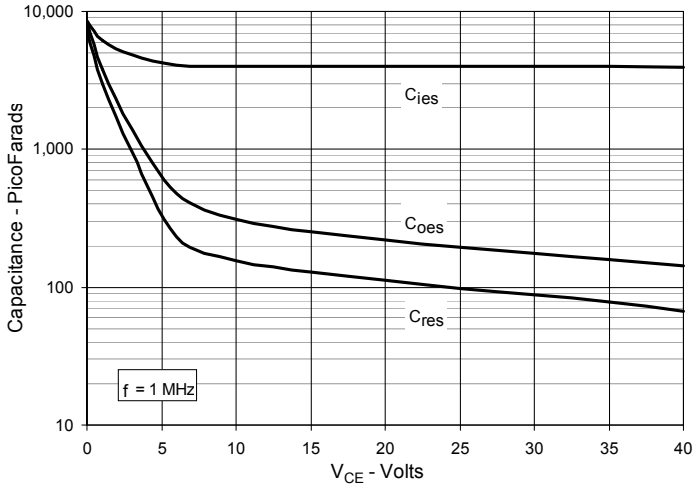


Fig. 11. Reverse-Bias Safe Operating Area

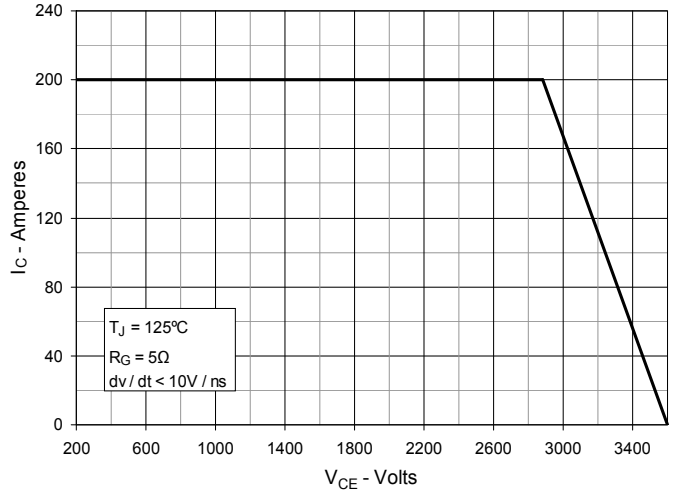


Fig. 12. Maximum Transient Thermal Impedance

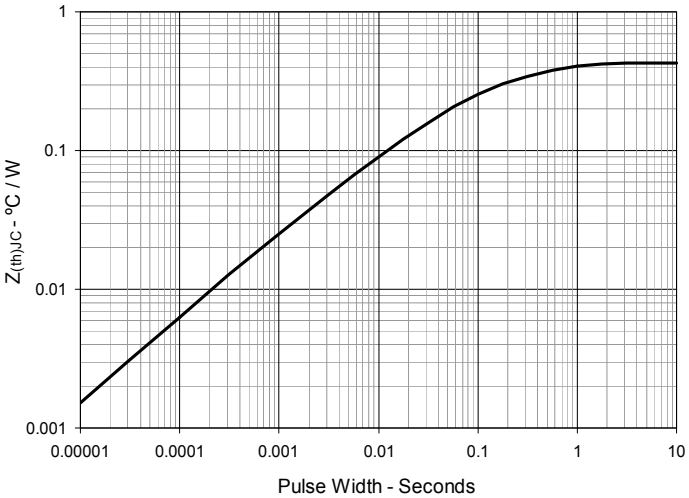


Fig. 13. Resistive Turn-on Rise Time vs. Junction Temperature

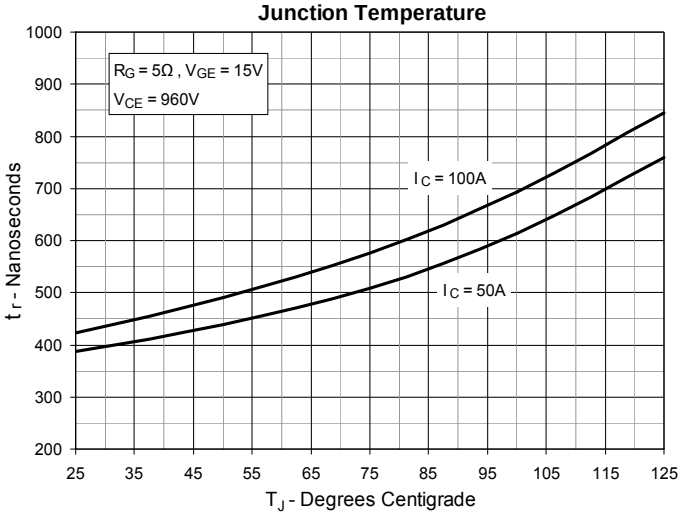


Fig. 14. Resistive Turn-on Rise Time vs. Collector Current

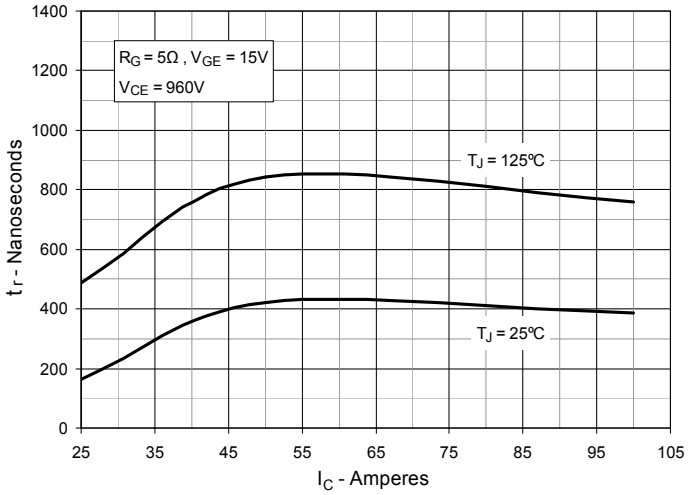


Fig. 15. Resistive Turn-on Switching Times vs. Gate Resistance

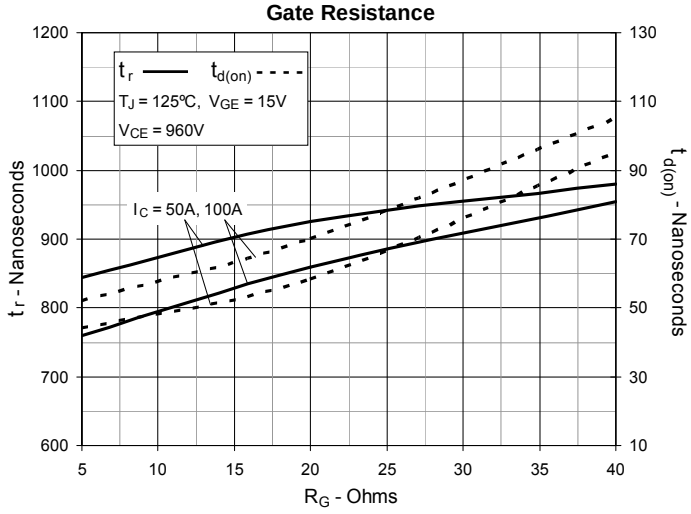


Fig. 16. Resistive Turn-off Switching Times vs. Junction Temperature

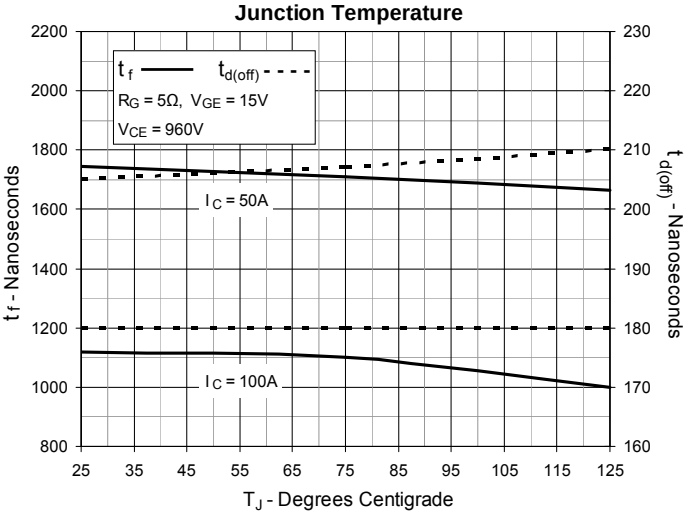


Fig. 17. Resistive Turn-off Switching Times vs. Collector Current

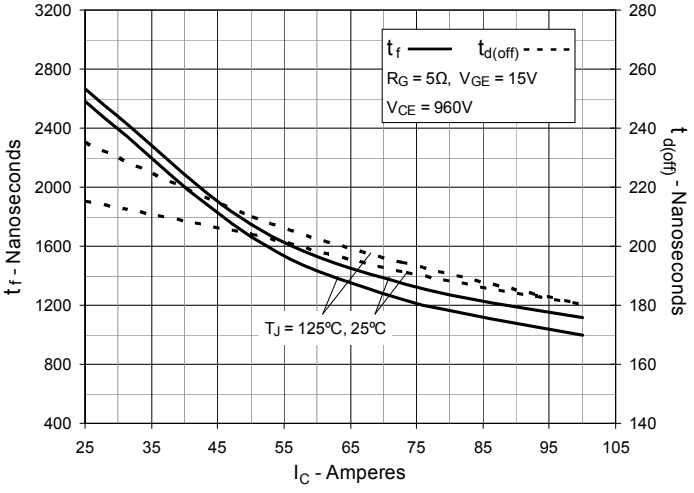


Fig. 18. Resistive Turn-off Switching Times vs. Gate Resistance

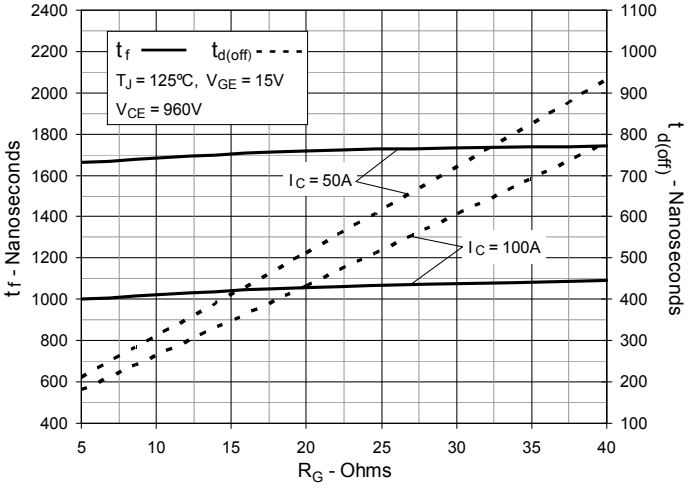


Fig. 19. Forward-Bias Safe Operating Area @ T_C = 25ºC

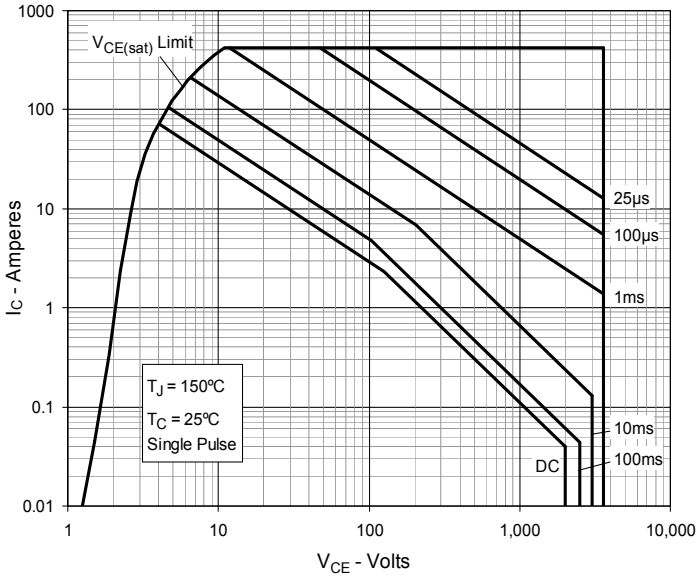


Fig. 20. Forward-Bias Safe Operating Area @ T_C = 75ºC